

### Features

- Suitable to small packages (SOT-353) Chip Size=0.71\*0.40mm
- 5 Array TVS
- High ESD protection level  
IEC61000-4-2(ESD) +/-15kV(Air) +/-8kV(Contact)

### Applications

- Computers
- Printers
- Communication systems
- Cellular phones handsets and accessories
- Wireline and wireless telephone sets
- Set top boxes

Item	Characteristics
Wafer Size	5inch
Chip Size	710*400um

### Maximum Ratings (Ta=25degC)

Symbol	Parameter	Value	Units
Ppk	Peak Power Dissipation @tp=8/20us (*1)	100	W
Ipp	Maximum Peak Pulse Current @tp=8/20us(*1)	8	A
Tstg	Storage Temperature Range	-40to+125	Deg C
Vpp	Electrostatic Discharge		
	IEC61000-4-2 Air Discharge (*1)	±15	kV
	IEC61000-4-2 Contact Discharge (*1)	±8	kV

(\*1) Rating value for reference on a SOT-23 package configuration (front: Au wire 35um, back: Au eutectic), mounted on PCB of 1.5cm by 2.5cm.

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## Electrical Characteristics (Ta=25degC)

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Ratings at 25degC ambient temperature unless otherwise specified.

Parameter	Symbol	Min	Typ.	Max	Unit	Condition
Breakdown Voltage	V <sub>BR</sub>	6.1	6.65	7.2	V	@1mA
Leakage Current	I <sub>R</sub>	-	-	1.0	uA	@V <sub>rwm</sub> = 3V
Forward Voltage	V <sub>F</sub>	-	-	0.9	V	@10mA
		-	-	1.25	V	@200mA
Capacitance	C <sub>j</sub>	-	50	-	pF	@0V,@1MHz
Clamping Voltage *1	V <sub>c</sub>	-	-	9.8	V	@I <sub>pp</sub> =5A
		-	-	12.5	V	@I <sub>pp</sub> =8A

\*1 Package=SOT-23 (front: Au wire 35um, back: Au eutectic) @tp=8/20us